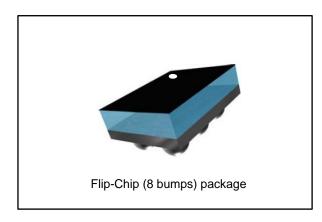


## **BALF-112X-01D3**

# 50 ohm nominal input / conjugate match balun CC1120, CC1125 (868-928 MHz), with integrated harmonic filter

Datasheet - production data



#### **Features**

- 50 Ω nominal input / conjugate match to CC1120, CC1125
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint

#### **Benefits**

- Very low profile (< 670 µm thickness)</li>
- High RF performance
- RF BOM and size reduction

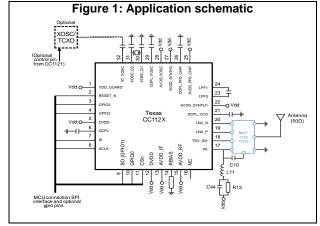
## **Applications**

 868 MHz and 928 MHz impedance-matched balun filter optimized for Texas Instruments<sup>®</sup> CC1120, CC1125, CC1175, CC1200 sub-GHz RFICs.

### **Description**

STMicroelectronics' BALF-112X-01D3 is an ultra-miniature balun, integrating both matching network and harmonics filter.

Matching impedance has been customized for the CC1120, CC1125, CC1175 and CC1200 transceivers from Texas Instruments. The device uses STMicroelectronics' IPD technology on a non-conductive glass substrate, which optimizes RF performance.



C10 is a DC block capacitor: 0402/100 pF/50 V

February 2017 DocID029407 Rev 2 1/10

Characteristics BALF-112X-01D3

## 1 Characteristics

Table 1: Absolute maximum ratings (limiting values)

Cumbal	Devemeter		Unit			
Symbol	Parameter	Min.	Тур.	Max.	Oilit	
P <sub>IN</sub>	Input power RFIN		ı	20	dBm	
V <sub>ESD</sub>	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 $\Omega$ , air discharge)	500	-		V	
	ESD ratings machine model (MM: $C = 200 \text{ pF}$ , $R = 25 \text{ W}$ , $L = 500 \text{ nH}$ )	250			V	
TOP	Operating temperature	-40	-	+85	°C	

Table 2: Electrical characteristics and RF performance ( $T_{amb}$  = 25 °C) RX balun

Comple of	Downwater	Test		Unit			
Symbol	Parameter	condition	Min.	Тур.	Max.	Unit	
Z <sub>RX</sub>	Nominal differential impedance			Match to CC112X		Ω	
Z <sub>ANT</sub>	Antenna impedance			50		Ω	
f	Frequency range (bandwidth)		866		928	MHz	
C24	Insertion loss in bandwidth	at 868 MHz	-2.3	-1.9		٩D	
S21 <sub>RX-ANT</sub>	insertion loss in bandwidth	at 928 MHz	-2.8	-2.4		dB	
044	Input return loss in bandwidth	at 868 MHz		-22	-20	40	
S11 <sub>ANT</sub>		at 928 MHz		-11	-9	dB	
Phase_imbal	Output phase imbalance	-10	-2.9	10	0		
Ampl_imbal	Output amplitude imbalance	-1	-0.3	1	dB		

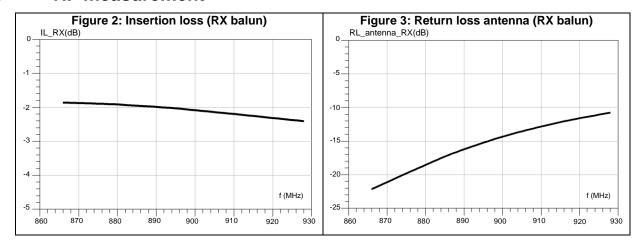
BALF-112X-01D3 Characteristics

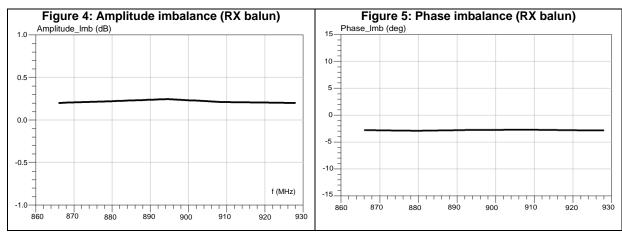
Table 3: Electrical characteristics and RF performance (T<sub>amb</sub> = 25 °C) TX filter

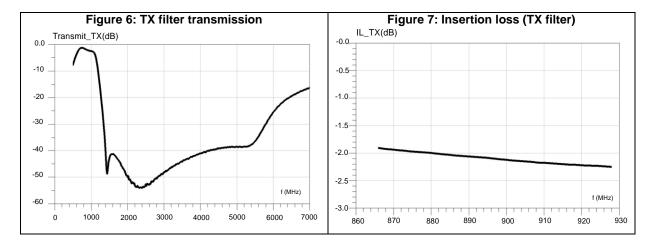
Symbol	Parameter	Test condition		Unit		
Symbol	Parameter	rest condition	Min.	Тур.	Max.	Onit
Z <sub>TX</sub>	Nominal TX impedance			Match to CC112X		Ω
Z <sub>ANT</sub>	Antenna impedance			50		Ω
f	Frequency range (bandwidth)		866		928	MHz
004	In a setion loss in boundarieth	at 868 MHz	-2.3	-1.9		10
S21 <sub>TX-ANT</sub>	Insertion loss in bandwidth	at 928 MHz	-2.7	-2.3		dB
044	Input return loss in	at 868 MHz		-8	-6	40
S11 <sub>ANT</sub>	bandwidth	at 928 MHz		-7	-5	dB
		Attenuation at 2 fo		-43	-41	
Att		Attenuation at 3 fo		-50	-46	
	Harmonic levels	Attenuation at 4 fo		-43	-40	dBm
		Attenuation at 5 fo		-39	-37	ubili
		Attenuation at 6 fo		-35	-33	
		Attenuation at 7 fo		-19	-17	

Characteristics BALF-112X-01D3

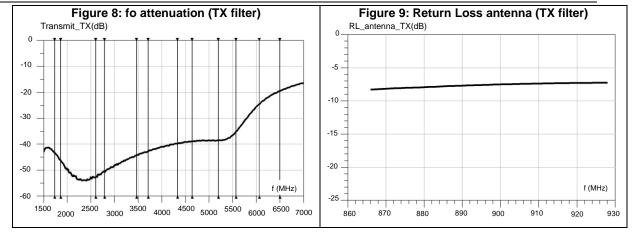
#### 1.1 RF measurement







BALF-112X-01D3 Characteristics



Package information BALF-112X-01D3

## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

## 2.1 Flip-Chip CSPG 0.4 package information

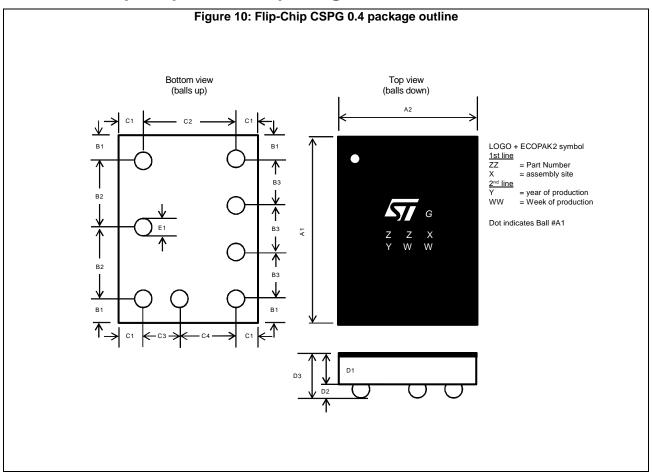


Table 4: Flip-Chip CSPG 0.4 mechanical data

Dimensions	Frequency	A1	A2	B1	B2	В3	C1	C2	С3	C4	D1	D2	D3	E1
BAL-112X-01D3	868 MHz	1950	1450	225	750	500	223	1004	400	604	425	205	630	255

BALF-112X-01D3 Package information

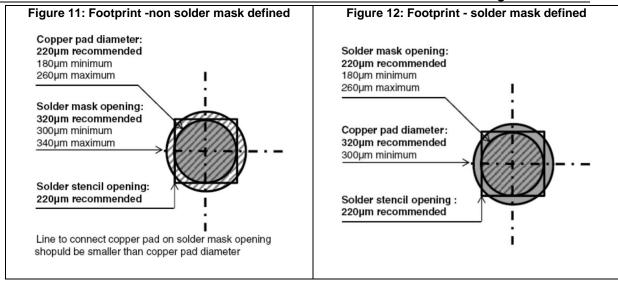


Figure 13: Ball assignment

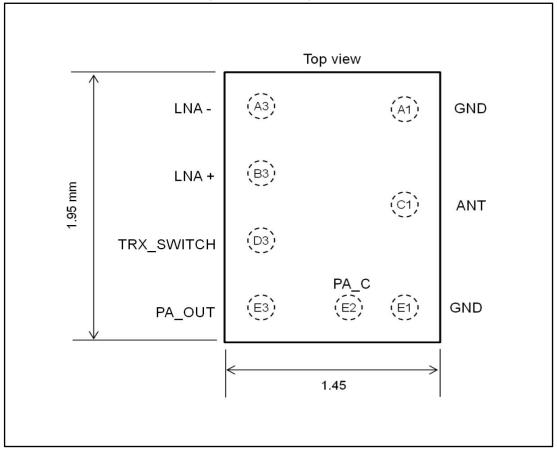
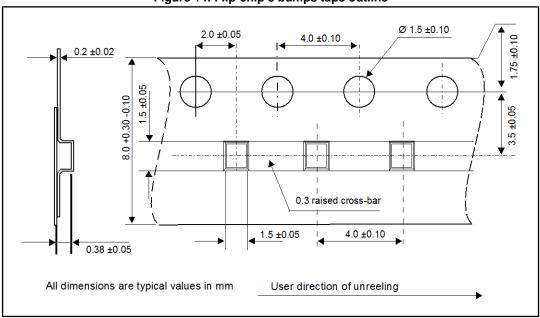


Table 5: Flip-Chip CSPG 0.4 ball description

Ball	Name	Designation
A1	GND	Ground
A3	3 LNA- Connect to LNA_N	
В3	LNA+	Connect to LNA_P
C1	ANT	Connect to antenna
D3	TRX_SW	Connect to TRX switch
E1	E1 GND Ground	
E2	PA_C Connect to PA output thru C10	
E3	PA_OUT	Connect to PA

# 2.2 Flip-chip 8 bumps packing information

Figure 14: Flip-chip 8 bumps tape outline



# 3 Ordering information

**Table 6: Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
BALF-112X-01D3	TF	CSPG	3.02 mg	5000	Tape and reel

# 4 Revision history

**Table 7: Document revision history** 

Date	Revision	Changes
04-Jul-2016	1	First issue.
20-Feb-2017	2	Updated Front page.

#### **IMPORTANT NOTICE - PLEASE READ CAREFULLY**

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2017 STMicroelectronics - All rights reserved

